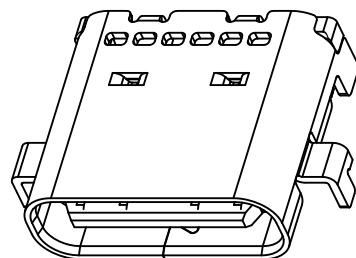
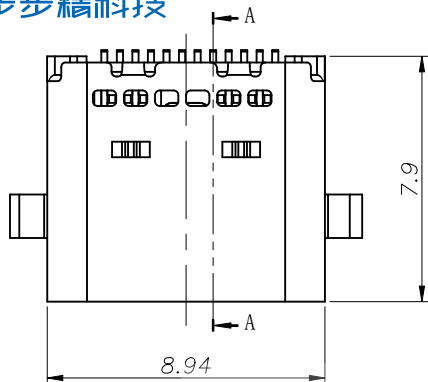


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 2.CONTACTS:COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL
- 5.EMI PLATE: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.
Au G/F PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW

2-2.FRONT SHELL:

Ni 30u" MIN. UNDER PLATED OVER ALL.

2-3.MID PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

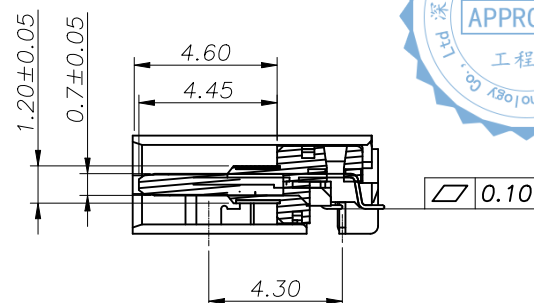
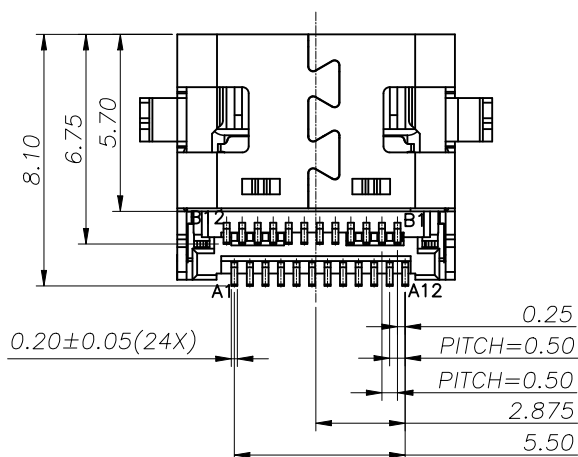
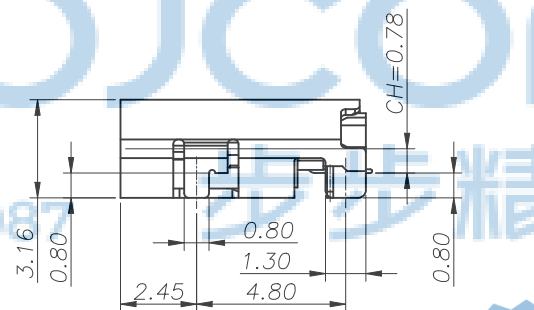
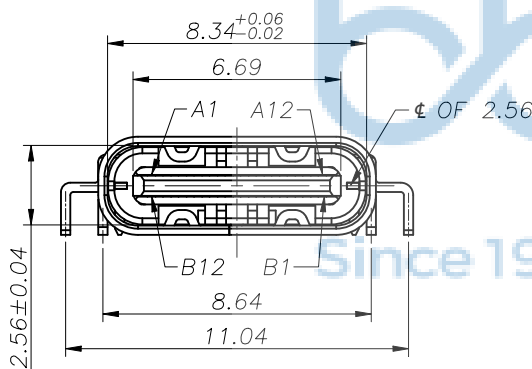
- 4-1. CURRENT RATING:5.0A
VOLTAGE RATING:5.0V
- 4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX.
SHIELD: 50mA/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mA.
- 4-3.INSULATION RESISTANCE: 100M Ω MIN
- 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

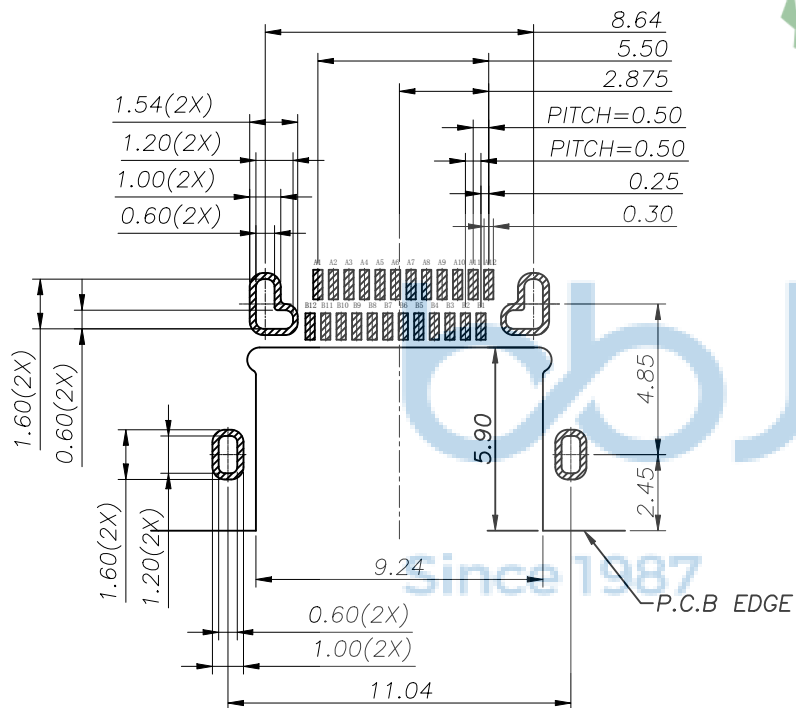
6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

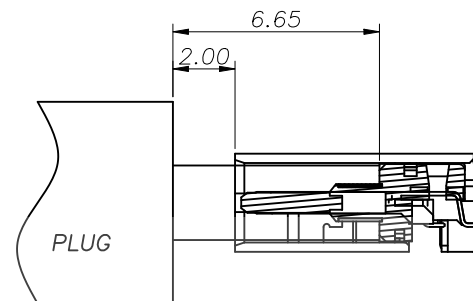


SECTION:A-A

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PDWG:NO: 0366-2	APPD. JM_Zheng	NAME: TYPE-C 24P 母座 沉板0.8 双排SMT 四脚插 L=7.90 CH=0.78 编带	
DR. TSP	CHKD. LYX	PJ. NO.: 126-221-240007-N5G	
		SIZE: A4 DRW NO.:	
		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3	



RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 0.60MM;DEFAULT TOLERANCE:±0.05



AFTER MATING

USB TYPE-C PIN ASSIGNMENTS

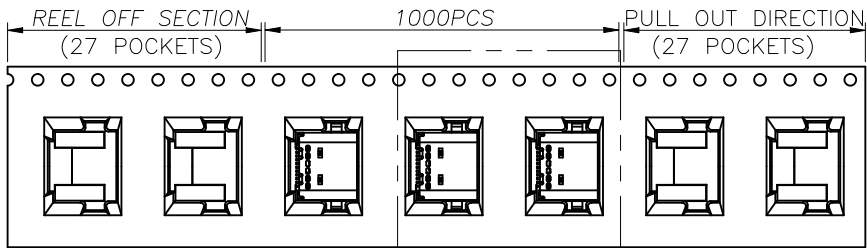
PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND



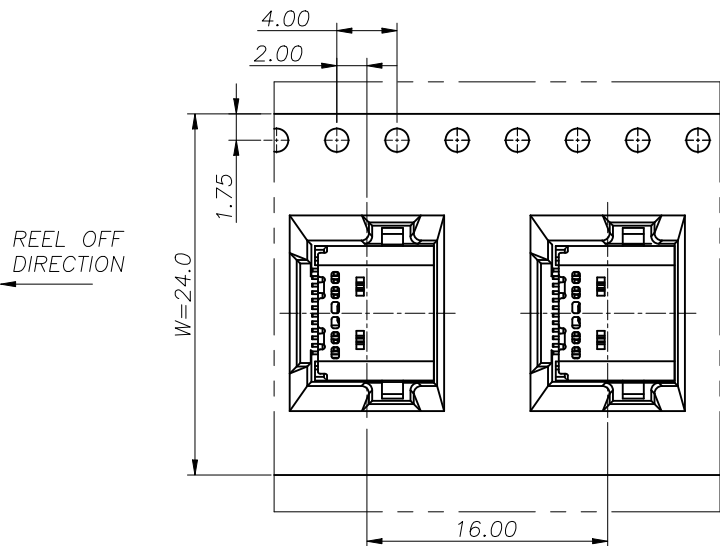
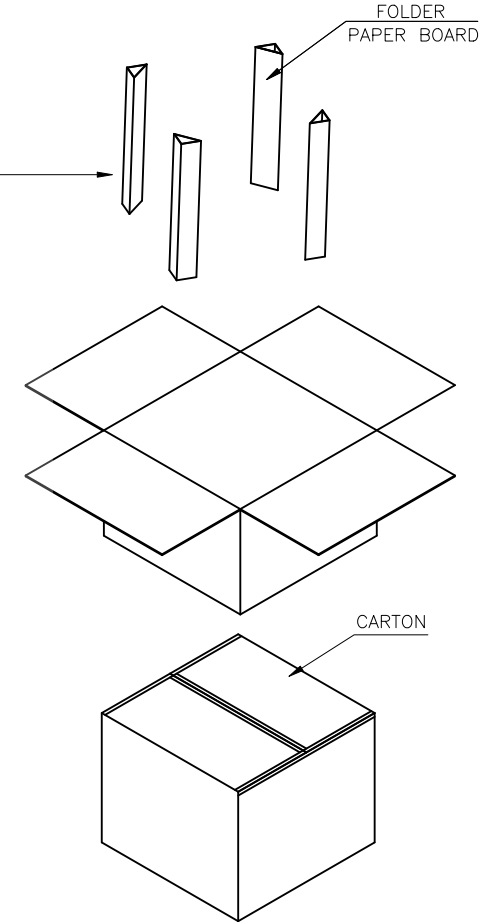
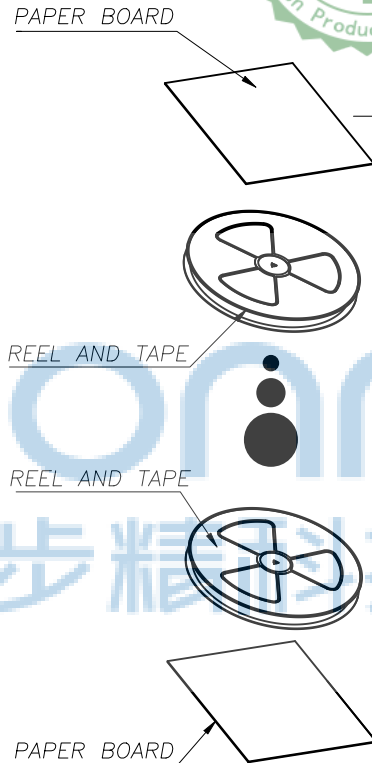
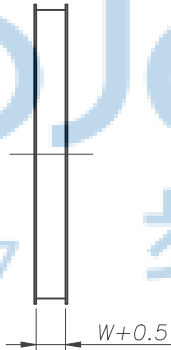
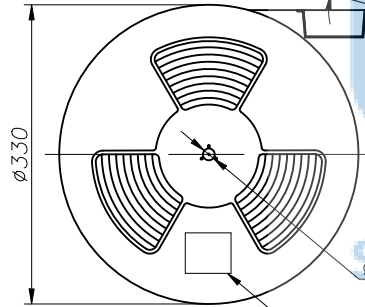
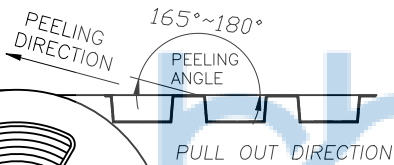
THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 .X: ±0.38 .XX: ±0.25 .XXX: ±0.13 X': ±3" X'': ±2" XX': ±1"		NAME: TYPE-C 24P 母座 沉板0.8 双排SMT 四脚插 L=7.90 CH=0.78 编带 APPD. JM_Zheng CHKD. LYX DR. TSP	
PDWG.NO: 0366-2		PJ. NO.: 126-221-240007-N5G SIZE: A4 DRW NO.:		FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/3	



REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



SEE DETAIL X



PULL OUT DIRECTION



	REEL	CARTON
CONNECTOR (PCS)	1000	10000

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PDWG:NO: 0366-2

深圳市步步精科技有限公司

NAME: TYPE-C 24P 母座 沉板0.8 双排SMT 四脚插 L=7.90 CH=0.78 编带

PJ. NO.: 126-221-240007-N5G

SIZE: A4 | DRW NO.:

FINISH: SEE NOTES | MAT'L.: SEE NOTES

SCALE: N/A | REV.: A0 | UNIT: mm | PAGE: 3/3

APPD.	JM_Zheng
CHKD.	LYX
DR.	TSP